

**Carrier element for ic module of chip card**

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**Abstract**

A support element for mounting into a chip card has a semiconductor chip (2) arranged on a conductive substrate (1) and electrically connected to the contact lugs (5, 6; 5, 7) of the latter. At least the semiconductor chip (2) and the bonding wires (3) for connecting it to the contact lugs (5, 6; 5, 7) are surrounded by a plastic material (4) so that the contact lugs (5, 6; 5, 7) project out of the plastic material (4) and form a conductive connection to the semiconductor chip (2). The contact lugs on one of the surfaces of the plastic material (4) form contact surfaces (5). In addition, at least two contact lugs form extensions (6; 7) of the contact surfaces (5) for connecting to the ends of a coil antenna.

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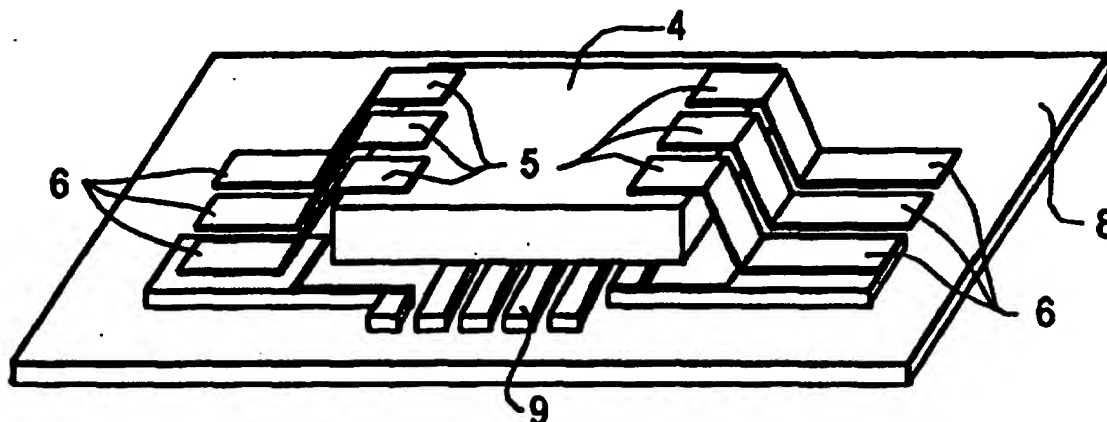
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(54) Bezeichnung: TRÄGERELEMENT



(57) Abstract

A support element for mounting into a chip card has a semiconductor chip (2) arranged on a conductive substrate (1) and electrically connected to the contact lugs (5, 6; 5, 7) of the latter. At least the semiconductor chip (2) and the bonding wires (3) for connecting it to the contact lugs (5, 6; 5, 7) are surrounded by a plastic material (4) so that the contact lugs (5, 6; 5, 7) project out of the plastic material (4) and form a conductive connection to the semiconductor chip (2). The contact lugs on one of the surfaces of the plastic material (4) form contact surfaces (5). In addition, at least two contact lugs form extensions (6; 7) of the contact surfaces (5) for connecting to the ends of a coil antenna.